

## **Features and Benefits**

- Built-in pre-drive IC and 3 bootstrap diodes as a high-side drive power supply
- CMOS compatible input (3.3 to 5 V)
- High-side gate driver using bootstrap circuit or floating power supply
- One pin for 7.5 V regulator output
- Built-in protection circuit for controlling power supply voltage drop
- Built-in overheat detection circuit (TD)
- Output of fault signal during operation of protection circuit
- Output current 1.5, 2, or 2.5 A
- Small SIP (SMA 24-pin)

## Packages: Power SIP





# Description

The SMA6820MP inverter power module (IPM) series provides a robust, highly-integrated solution for optimally controlling 3-phase motor power inverter systems and variable speed control systems used in energy-conserving designs to drive motors of residential and commercial appliances. These ICs take 230 VAC input voltage, and up to 2.5 A (continuous) output current. They can withstand voltages of up to 500 V (MOSFET breakdown voltage).

The SMA6820MP power package includes an IC with all of the necessary power elements (six MOSFETs) and pre-driver ICs (two) needed to configure the main circuit of an inverter. This enables the main circuit of the inverter to be configured with fewer external components than traditional designs.

Applications include residential white goods (home applications) and commercial appliance motor control:

- Air conditioner fan
- Small ventilation fan
- Dishwasher pump



Figure 1. Driver block diagrams.

### **Selection Guide**

		MOSFET Breakdown	Output Current			
Part Number	Packing	Voltage, V <sub>DSS</sub> (min) (V)	Continuous, I <sub>O</sub> (max) (A)	Pulsed, I <sub>OP</sub> (max) (A)		
SMA6821MP	18 pieces per tube	250	2	4		
SMA6822MP	18 pieces per tube	500	1.5	3		
SMA6823MP	18 pieces per tube	500	2.5	5		

### Absolute Maximum Ratings, valid at T<sub>A</sub> = 25°C

Characteristic	Symbol		Remarks	Rating	Unit
		SMA6821MP		250	V
MOSFET Breakdown Voltage	V <sub>DSS</sub>	SMA6822MP	V <sub>CC</sub> = 15 V, I <sub>D</sub> = 100 μA, V <sub>IN</sub> = 0 V	500	V
		SMA6823MP		500	V
Logic Supply Voltage	V <sub>CC</sub>	Between VCC a	and COM	20	V
Bootstrap Voltage	V <sub>BS</sub>	Between VB an	d HS (U,V, and W phases)	20	V
		SMA6821MP		2	A
Output Current, Continuous	lo	SMA6822MP	T <sub>C</sub> = 25°C	1.5	A
		SMA6823MP		2.5	A
		SMA6821MP		4	A
Output Current, Pulsed	I <sub>OP</sub>	SMA6822MP	PW ≤ 100 µs, duty cycle = 1%	3	A
		SMA6823MP		5	A
Output Current for Regulator	I <sub>REG</sub>			35	mA
Input Voltage	V <sub>IN</sub>	HINx and LINx	pins	-0.5 to 7	V
Allowable Power Dissipation	PD	T <sub>C</sub> = 25°C		28	W
Thermal Resistance (Junction to Case)	R <sub>eJC</sub>	All elements op	erating	4.46	°C/W
Thermal Resistance (Junction to Air)	R <sub>0JA</sub>	All elements op	erating	31.25	°C/W
Case Operating Temperature	T <sub>COP</sub>			-20 to 100	°C
Junction Temperature (MOSFET)	TJ			150	°C
Storage Temperature	T <sub>stg</sub>			-40 to 150	°C

### **Recommended Operating Conditions**

Characteristic	Symbol		Remarks	Min.	Тур.	Max.	Units
		SMA6821MP		-	150	200	V
Main Supply Voltage	V <sub>BB</sub>	SMA6822MP	Between VBB and LS	_	300	400	V
		SMA6823MP		-	300	400	V
Logic Supply Voltage	V <sub>CC</sub>	Between VCC ar	nd COM	13.5	-	16.5	V
Dead Time	t <sub>dead</sub>			1.5	-	-	μs
Junction Temperature	TJ			-	-	125	°C

All performance characteristics given are typical values for circuit or system baseline design only and are at the nominal operating voltage and an ambient temperature,  $T_A$ , of 25°C, unless otherwise stated.





### **Typical Application Diagram**



### NOTE:

- All of the input pins are connected to GND with internal pull-down resistors rated at 100 k $\Omega$ , however, an external pull-down resistor may be required to secure stable condition of the inputs if high impedance conditions are applied to them.
- The external electrolytic capacitors should be placed as close to the IC as possible, in order to avoid malfunctions from external noise interference. Put a ceramic capacitor in parallel with the electrolytic capacitor if further reduction of noise susceptibility is necessary.





#### ELECTRICAL CHARACTERISTICS, valid at T<sub>A</sub>=25°C, unless otherwise noted

Characteristics	Symbol	Conditions	Min	Тур	Max	Units
Logic Supply Voltage	V <sub>CC</sub>	Between VCC and COM	13.5	15	16.5	V
Logic Supply Current	Icc	V <sub>CC</sub> = 15 V, I <sub>REG</sub> = 0 A	_	4	6	mA
Input Voltage	VIH	V <sub>CC</sub> = 15 V, output on	-	2.0	2.5	V
Input Voltage	VIL	V <sub>CC</sub> = 15 V, output off	1.0	1.5	-	V
Input Voltage Hysteresis	V <sub>lhys</sub>	V <sub>CC</sub> = 15 V	-	0.5	-	V
Input Current	IIH	High side, $V_{CC}$ = 15 V, $V_{IN}$ = 5 V	-	50	100	μA
Input Current	IIL	Low side, $V_{CC}$ = 15 V, $V_{IN}$ = 0 V	-	-	2	μA
	V <sub>UVHL</sub>	High side, between VPx and LL V, or W	9.0	10.0	11.0	V
	V <sub>UVHH</sub>	High side, between VBx and U, V, or W	9.5	10.5	11.5	V
Linder reltage Leek Out	V <sub>UVHhys</sub>	High side, hysteresis	-	0.5	_	V
Undervoltage Lock Out	V <sub>UVLL</sub>	Low side between VCC2 and COM2	10.0	11.0	12.0	V
	V <sub>UVLH</sub>	Low side, between VCC2 and COM2		11.5	12.5	V
	V <sub>UVLhys</sub>	Low side, hysteresis	-	0.5	_	V
	V <sub>FOL</sub>		0	_	1.0	V
FO Terminal Output Voltage	V <sub>FOH</sub>	V <sub>CC</sub> = 15 V		_	5.5	V
Overtemperature DetectionThreshold Temperature (Activation and Deactivation)	T <sub>DH</sub>		135	150	165	°C
	T <sub>DL</sub>	V <sub>CC</sub> = 15 V, no heatsink		120	135	°C
	T <sub>Dhys</sub>		_	30	_	°C
Output Voltage for Regulator	V <sub>REG</sub>	I <sub>REG</sub> = 35 mA	6.75	7.5	8.25	V
		SMA6821MP V <sub>R</sub> = 250 V	-	_	10	μA
Bootstrap Diode Leakage Current	I <sub>LBD</sub>	SMA6822MP V <sub>R</sub> = 500 V	_	_	10	μA
		SMA6823MP V <sub>R</sub> = 500 V	-	_	10	μA
Bootstrap Diode Forward Voltage	V <sub>FBD</sub>	I <sub>F</sub> = 0.15 A	_	1.1	1.3	V
Bootstrap Diode Series Resistor	R <sub>BD</sub>		_	22	_	Ω
		SMA6821MP	250	_	_	V
MOSFET Breakdown Voltage	V <sub>DSS</sub>	SMA6822MP V <sub>CC</sub> = 15 V, I <sub>D</sub> = 100 μA, V <sub>IN</sub> = 0 V	500	_	_	V
		SMA6823MP	500	_	_	V
		SMA6821MP V <sub>CC</sub> = 15 V, V <sub>DS</sub> = 250 V, V <sub>IN</sub> = 0 V	_	_	100	μA
MOSFET Leakage Current	I <sub>DSS</sub>	SMA6822MP V <sub>CC</sub> = 15 V, V <sub>DS</sub> = 500 V, V <sub>IN</sub> = 0 V	_	_	100	μA
-		SMA6823MP V <sub>CC</sub> = 15 V, V <sub>DS</sub> = 500 V, V <sub>IN</sub> = 0 V	_	_	100	μA
		SMA6821MP V <sub>CC</sub> = 15 V, I <sub>D</sub> = 1.0 A, V <sub>IN</sub> = 5 V	-	1.4	1.8	Ω
MOSFET On State Resistance	R <sub>DS(on)</sub>	SMA6822MP V <sub>CC</sub> = 15 V, I <sub>D</sub> = 1.0 A, V <sub>IN</sub> = 5 V	_	3.6	4	Ω
		SMA6823MP V <sub>CC</sub> = 15 V, I <sub>D</sub> = 1.5 A, V <sub>IN</sub> = 5 V	_	2.0	2.4	Ω
		SMA6821MP V <sub>CC</sub> = 15 V, I <sub>SD</sub> = 1.0 A, V <sub>IN</sub> = 0 V	_	1.1	1.5	V
MOSFET Diode Forward Voltage	V <sub>SD</sub>	SMA6822MP V <sub>CC</sub> = 15 V, I <sub>SD</sub> = 1.0 A, V <sub>IN</sub> = 0 V	_	1	1.5	V
-		SMA6823MP V <sub>CC</sub> = 15 V, I <sub>SD</sub> = 1.5 A, V <sub>IN</sub> = 0 V	_	1	1.5	V





#### SMA6821MP SWITCHING CHARACTERISTICS, valid at T\_A=25°C, unless otherwise noted

Characteristics	Symbol	Conditions	Min	Тур	Max	Units
	t <sub>dH(on)</sub>	$V_{BB}$ = 150 V, $V_{CC}$ = 15 V, $I_D$ = 2 A, 0 V ≤ $V_{IN}$ ≤ 5 V	-	450	-	ns
	t <sub>rH</sub>		-	100	-	ns
Switching Time, High Side	t <sub>rr</sub>		-	90	-	ns
	t <sub>dH(off)</sub>		-	350	-	ns
	t <sub>fH</sub>		-	20	-	ns
	t <sub>dL(on)</sub>	$V_{BB}$ = 150 V, $V_{CC}$ = 15 V, $I_{D}$ = 2 A, 0 V ≤ $V_{IN}$ ≤ 5 V	-	550	-	ns
	t <sub>rL</sub>		-	110	-	ns
Switching Time, Low Side	t <sub>rr</sub>		-	90	-	ns
	t <sub>dL(off)</sub>		-	360	_	ns
	t <sub>fL</sub>		-	20	-	ns

#### SMA6822MP SWITCHING CHARACTERISTICS, valid at $T_{A} {=} 25^{\circ} \text{C},$ unless otherwise noted

Characteristics	Symbol	Conditions	Min	Тур	Max	Units
	t <sub>dH(on)</sub>	$V_{BB}$ = 300 V, $V_{CC}$ = 15 V, $I_{D}$ = 1.5 A, 0 V ≤ $V_{IN}$ ≤ 5 V	-	550	-	ns
	t <sub>rH</sub>		-	100	-	ns
Switching Time, High Side	t <sub>rr</sub>		_	120	-	ns
	t <sub>dH(off)</sub>		-	420	-	ns
	t <sub>fH</sub>		-	30	-	ns
	t <sub>dL(on)</sub>	$V_{BB}$ = 300 V, $V_{CC}$ = 15 V, $I_{D}$ = 1.5 A, 0 V ≤ $V_{IN}$ ≤ 5 V	_	570	-	ns
	t <sub>rL</sub>		-	100	-	ns
Switching Time, Low Side	t <sub>rr</sub>		-	120	-	ns
	t <sub>dL(off)</sub>		_	450	-	ns
	t <sub>fL</sub>		-	30	-	ns

#### SMA6823MP SWITCHING CHARACTERISTICS, valid at T<sub>A</sub>=25°C, unless otherwise noted

Characteristics	Symbol	Conditions	Min	Тур	Max	Units
	t <sub>dH(on)</sub>	$V_{BB}$ = 300 V, $V_{CC}$ = 15 V, $I_{D}$ = 2.5 A, 0 V ≤ $V_{IN}$ ≤ 5 V	-	640	-	ns
	t <sub>rH</sub>		-	100	-	ns
Switching Time, High Side	t <sub>rr</sub>		-	150	-	ns
	t <sub>dH(off)</sub>		-	520	-	ns
	t <sub>fH</sub>		-	30	_	ns
	t <sub>dL(on)</sub>	$V_{BB}$ = 300 V, $V_{CC}$ = 15 V, $I_D$ = 2.5 A, 0 V ≤ $V_{IN}$ ≤ 5 V	-	650	-	ns
	t <sub>rL</sub>		-	100	-	ns
Switching Time, Low Side	t <sub>rr</sub>		-	150	-	ns
	t <sub>dL(off)</sub>		-	580	-	ns
	t <sub>fL</sub>		-	30	-	ns





### High Side Driver Input/Output Timing Diagrams



After UVLO is released, IC operation is started by the first rising edge of input

Low Side Driver Input/Output Timing Diagrams







### **Pin-out Diagrams**



Chamfer on Opposite Side

### **Terminal List Table**

Number	Name	Function
1	VB1	High side bootstrap terminal (U phase)
2	VB2	High side bootstrap terminal (V phase)
3	VD	Bootstrap diode anode terminal
4	VB3	High side bootstrap terminal (W phase)
5	VCC1	High side logic supply voltage
6	COM1	High side logic GND terminal
7	HIN3	High side input terminal (W phase)
8	HIN2	High side input terminal (V phase)
9	HIN1	High side input terminal (U phase)
10	VBB1	Main supply voltage 1 (connect to VBB2 externally)
11	VBB2	Main supply voltage 2 (connect to VBB1 externally)
12	W1	Output of W phase (connect to W2 externally)
13	V	Output of V phase
14	W2	Output of W phase (connect to W1 externally)
15	LS2	Low side source terminal (connect to LS1 externally)
16	VREG	Internal regulator output terminal
17	LS1	Low side source terminal (connect to LS2 externally)
18	LIN3	Low side input terminal (W phase)
19	LIN2	Low side input terminal (V phase)
20	LIN1	Low side input terminal (U phase)
21	COM2	Low side GND terminal
22	FO	Overtemperature and low-side UVLO fault-signal output
23	VCC2	Low side logic supply voltage
24	U	Output of U phase





# Package Outline Drawing

Leadform 2451

Dual rows, 24 alternating pins; pins bent 90° for horizontal case mounting; pin #1 in outer row



SanKen



# Package Outline Drawing

Leadform 2452

Dual rows, 24 alternating pins; vertical case mounting; pin #1 opposite chamfer side





















**WARNING** — These devices are designed to be operated at lethal voltages and energy levels. Circuit designs that embody these components must conform with applicable safety requirements. Precautions must be taken to prevent accidental contact with power-line potentials. Do not connect grounded test equipment.

The use of an isolation transformer is recommended during circuit development and breadboarding.

Because reliability can be affected adversely by improper storage environments and handling methods, please observe the following cautions.

#### **Cautions for Storage**

- Ensure that storage conditions comply with the standard temperature (5°C to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of products that have been stored for a long time.

#### **Cautions for Testing and Handling**

When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing device, shorts between adjacent products, and shorts to the heatsink.

#### **Remarks About Using Silicone Grease with a Heatsink**

- When silicone grease is used in mounting this product on a heatsink, it shall be applied evenly and thinly. If more silicone grease than required is applied, it may produce stress.
- Volatile-type silicone greases may permeate the product and produce cracks after long periods of time, resulting in reduced heat radiation effect, and possibly shortening the lifetime of the product.
- Our recommended silicone greases for heat radiation purposes, which will not cause any adverse effect on the product life, are indicated below:

Туре	Suppliers
G746	Shin-Etsu Chemical Co., Ltd.
YG6260	Momentive Performance Materials, Inc.
SC102	Dow Corning Toray Silicone Co., Ltd.

#### Soldering

- When soldering the products, please be sure to minimize the working time, within the following limits: 260±5°C 10 s 380±10°C 5 s
- Soldering iron should be at a distance of at least 1.5 mm from the body of the products

#### Electrostatic Discharge

- When handling the products, operator must be grounded. Grounded wrist straps worn should have at least 1 MΩ of resistance to ground to prevent shock hazard.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of soldering irons or the solder bath must be grounded in other to prevent leak voltages generated by them from being applied to the products.
- The products should always be stored and transported in our shipping containers or conductive containers, or be wrapped in aluminum foil.





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